INTEGRALLY PACKAGED IMAGING MODULE

Abstract of the Disclosure

An integrally packaged imaging module includes an integrated circuit (IC), including an image sensing device formed on a semiconductor substrate, and wafer level packaging enclosing the IC. The wafer level packaging includes a transparent enclosure portion adapted to permit image acquisition of an image by the image sensing device over a desired range of wavelengths, and a first spacing structure providing a cavity between an inner surface of the transparent enclosure portion and the image sensing device. A depth of the cavity is configurable along an axis perpendicular to the semiconductor substrate to control a distance between an outer surface of the transparent enclosure portion and the image sensing device.